Session Title:	[TB2] Integration and Interposer
Session Date:	November 21 (Tue.), 2023
Session Time:	10:20-12:10
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Changhwan Choi (Hanyang Univ., Korea)

[TB2-1] [Invited] 10:20-10:50

Technology Trend of the Interposer for 2.5D SiP

Minsuk Suh (SK hynix, Korea)

[TB2-2] [Invited] 10:50-11:10

2.5D Interposer Technologies for Heterogeneous Integration

Gu-Sung Kim (Kangnam Univ., Korea)

[TB2-3] [Invited] 11:10-11:30

High-Performance $TiO_2/ZrO_2/TiO_2$ Thin Film Capacitor by Plasma-Assisted Atomic Layer Annealing

Seunghyeon Lee, Geongu Han, Keun Hoi Kim (Seoul Nat'l Univ. of Science and Tech., Korea), Dohyun Go (Univ. of California San Diego, USA), and Jihwan An (POSTECH, Korea)

[TB2-4] [Invited] 11:30-11:50

Metal-Oxide Based Thermal Interface Materials for Improvement of Heat Transfer Characteristics

Sangmin Kim, Uijin Jung, Wonjun Heo, Sungmin Jung, and Jinsub Park (Hanyang Univ., Korea)

[TB2-5] 11:50-12:10

FEOL Process-Based Redistribution Layer (RDL) Formation

Sun Bum Kim, Chan Seul Lee, Gyu Lee Kim, Sangyeun Park, Doheon Koo, Yeongu Choi, Joo Young Pyun, Chang Hoon Lee, Hongyun So, Kwan Kyu Park, and Changhwan Choi (Hanyang Univ., Korea)